RENESAS

HRW0202B

Silicon Schottky Barrier Diode for Rectifying

REJ03G0153-0200Z (Previous: ADE-208-345A) Rev.2.00 Dec.15.2003

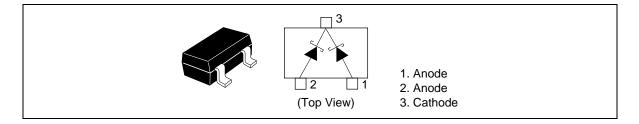
Features

- Low forward voltage drop and suitable for high efficiency rectifying.
- MPAK Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Туре No.	Laser Mark	Package Code
HRW0202B	S18	МРАК

Pin Arrangement





Absolute Maximum Ratings *1

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit	
Repetitive peak reverse voltage	V _{RMM} * ²	20	V	
Average rectified current	l ₀ * ²	200	mA	
Non-Repetitive peak forward surge current	I _{FSM} * ³	3	А	
Junction temperature	Tj	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

Notes: 1. Two device total

2. See from Fig.4 to Fig.7

3. 10ms sine wave 1 pulse

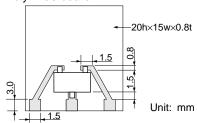
Electrical Characteristics ^{*1}

 $(Ta = 25^{\circ}C)$

ltem	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _F	_	_	0.42	V	I _F = 100 mA
Reverse current	I _R	_	_	10	μΑ	V _R = 20 V
Thermal resistance	R _{th(j-a)}	_	400	_	°C/W	Polyimide board ^{*2}

Notes: 1. Per one device

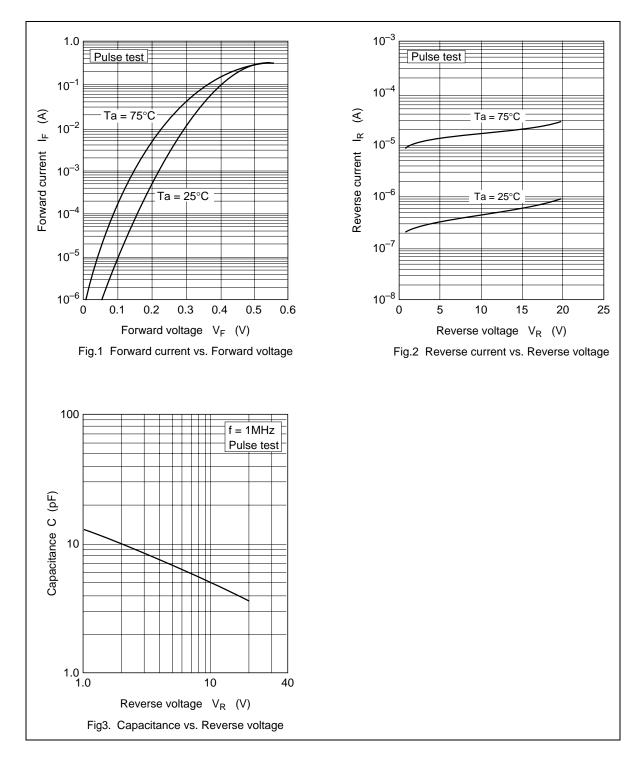
2. Polyimide board





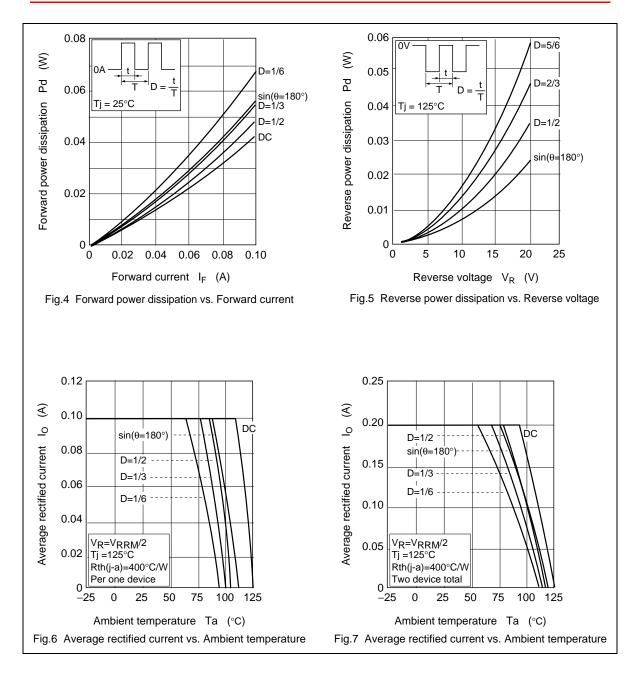
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Main Characteristic



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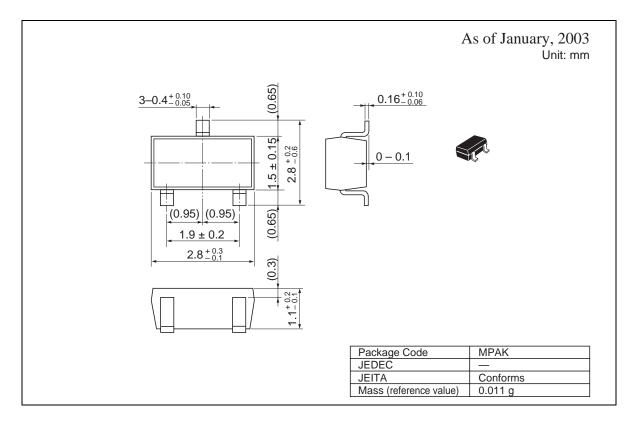
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Package Dimensions





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